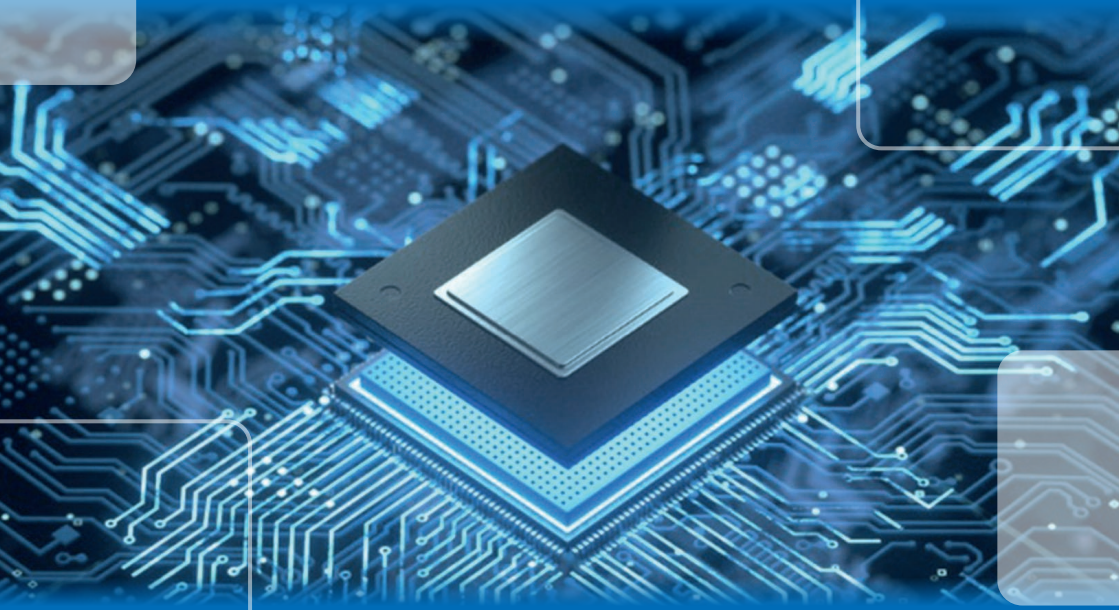
Semiconductor Day 2026



SWISSMEM

Invitation to the 2nd Swiss Semiconductor Industry Day 2026

We are pleased to invite you to a **full-day event dedicated to Switzerland's activities in the semiconductor field**, bringing together leading representatives from public institutions, research organizations, and private companies.

This unique event will provide an in-depth view of Switzerland's role within the global semiconductor value chain — from **chip design to metrology and advanced packaging.** Participants will share first-hand insights into their organizations' strategies, innovations, and perspectives on the **current challenges and opportunities** shaping the industry.

Throughout the day, keynote presentations and a panel discussion will explore key themes such as technological trends, supply chain resilience, talent development, and collaborative opportunities across the ecosystem.

What to Expect

Keynotes: Gain forward-looking insights into the current global semiconductor supply chain, limitations in global trade and opportunities from a military perspective.

Industry Highlights: Listen to trends, challenges and opportunities from Switzerland-based semiconductor manufacturers and learn how their innovations contribute to advancing technology and competitiveness along the semiconductor value chain

Collaborative Networking: Connect with innovators, researchers, and decision-makers during our networking sessions, lunch and evening apéro — fostering new ideas, partnerships, and collaborations.

Date

Wednesday, 18.03.2026, 09:00–18:30

Program	Title	Speaker	Company
9:00 – 9:20	Welcome and Introduction	Dr. Adriaan Spierings Cemal Aydogan Alexandre Pauchard Matthieu Aubert Dr. Yasin Ekinci	Swissmem Hitachi Energy CSEM invest Neuchâtel PSI
9:20 – 10:20	**Session 1:** Geopolitical Aspects impacting the semiconductor industry	Dr. Adriaan Spierings	Swissmem
10:20 – 10:50	Break and networking		
10:50 – 12:00	**Session 2:** Trends, challenges and opportunities for the Swiss industry in chip design	Dr. Alain-Serge Porret	CSEM
12 :00 – 13 :15	Lunch		
13 :15 – 14 :35	**Session 3:** Trends, challenges and opportunities for the Swiss industry in metrology along the semiconductor value chain	Dr. Yasin Ekinci	PSI
14:35 – 15:05	Break		
15:05 – 16:15	**Session 4:** Trends, challenges and opportunities for the Swiss industry in advanced packaging	Cemal Aydogan	Hitachi Energy AG
16:15 – 16:45	**Panel Discussion**	Hans Priem	VDL ETG
16:45 – 17:00	**Concluding remarks:** The Swiss Semiconductur Day today and in the future	Cemal Aydogan Dr. Adriaan Spierings	Hitachi Energy AG Swissmem
From 17:00 on	Networking and Apéro		

Organization committee

Oliver Kunz,
Carl Zeiss SMT

Alain-Serge Porret,
CSEM

Beatriz Tur,
CSEM

Cemal Aydogan,
Hitachi Energy

Yasin Ekinci,
PSI

Isabelle Haipt,
Swissmem

Adriaan Spierings,
Swissmem

Hans Priem,
VDL ETG Switzerland

Session 1:
Geopolitical Aspects impacting the semiconductor industry

Session moderation		**Dr. Adriaan Spierings, Swissmem**
9:20 – 9:35	Securing Semiconductor Exports under Swiss and Global Trade Rules	Seraina Frost, SECO
9:35 – 9:50	Securing the Global Supply Chain in the Era of Increased Geopolitical Competition	Dr. Ivan Zaccagnini, ETH Center for Security Studies CSS
9:50 – 10:05	Military trends and needs for semiconductor solutions	Dr. Thomas Rothacher, armasuisse
10:05 – 10:20	Semiconductor-technology as an enabler for modern Defence Systems	Reto Maurer, Dipl. Masch. Ing. FH, Rheinmetall & President Swissmem ASD

State Secretariat for Economic Affairs SECO
Federal Department of Economic Affairs, Education and Research EAER Bern

Schweizerische Eidgenossenschaft
Confédération suisse
Confederazione Svizzera
Confederaziun svizra

Swiss Confederation

Federal Department of Economic Affairs, Education and Research EAER
State Secretariat for Economic Affairs SECO

Seraina Frost,
Co-Deputy Head of Export Controls for Industrial Goods, SECO
She holds a Master of Arts in Intelligence and International Security from the Department of War Studies at King's College London and was a Fellow of the United Nations Program on Disarmament in 2011. Since 2012, she has worked in export controls, specialising in the multilateral negotiation of goods control lists, including semiconductor-related items under the Wassenaar Arrangement. From 2020 to 2024, she co-chaired and later chaired the Missile Technology Control Regime's Technical Expert Meeting.

Abstract
Advanced semiconductor manufacturing equipment and AI chips have become a central focus of export controls over the past five years. States with firms holding key technologies have introduced national controls, followed by efforts to multilateralise them within export control regimes. While some members of the Wassenaar Arrangement are gradually expanding controls on equipment, critical components, and related technologies, restrictions on rare earths are emerging in response. This presentation provides insights into how SECO navigates these developments, securing Switzerland's economic interests by enabling legitimate exports and ensuring continued access to essential raw materials and technologies.

ETH-Center of Security Studies CSS, Zürich

CSS ETH Zürich

Dr. Ivan Zaccagnini, Researcher in Technology and Geopolitics, Center for Security Studies at ETH Zurich

He is actually enrolled in a joint Ph.D. programme between the LUISS Guido Carli University in Rome and the Centre for Security, Diplomacy and Strategy (CSDS) of the Vrije Universiteit Brussel in Brussels.

His research interests focus on Emerging and Disruptive Technologies, Future of Warfare, and Great Power Competition. The provisional title of his Ph.D. thesis is "Europe's Place in US-China Technology Competition. Insights from Wedging, Binding and Dynamic Sequencing."

Abstract

The semiconductor value chain has become a critical arena of geopolitical competition, as microchips underpin both commercial innovation and advanced military systems. Intensifying US–China rivalry has transformed this sector into a strategic battleground, driving decoupling, export controls, and a broader technology trade war. Europe, deeply embedded in this interdependent ecosystem, must navigate external pressures exerted by the two great powers. Yet it is not merely a passive player: niches, such as the Netherlands' lithography leadership and key firms in Germany, Italy, and Austria, provide the foundations for strategic agency. Europe's ability to leverage its market position and value-chain configuration can shape its future autonomy and resilience.

Armasuisse, Bern

Schweizerische Eidgenossenschaft
Confédération suisse
Confederazione Svizzera
Confederaziun svizra

armasuisse

Dr. Thomas Rothacher, Deputy Chief of Armament, Federal Department of Defence, Civil Protection and Sport, Switzerland

Thomas Rothacher attended grammar school after completing his training as a laboratory assistant. He later studied physics at the University of Bern, where he obtained his doctorate in 2004. His research was in the field of laser technology. At the same time as working on his PhD, Tom Rothacher started in the technical department at armasuisse. He has managed various departments there, and since 2013 he has been Director of Science and Technology, the technology center of the DDPS. In this role, he is responsible for technical military research and innovation within the DDPS. Since 2015 he is also an elected member of a local municipal council. In 2020, he was appointed Deputy National Armaments Director by the Federal Council. Since June 2024, he has been responsible for the newly established Taskforce Drones (TFD), serving as a permanent testbed until at least 2027. Tom is married to Christine, and together they have two sons.

Abstract

The Swiss Armed Forces rely on a vast range of technologies and nearly all of its systems depend on semiconductor components. Thus, Switzerland's security challenge is to ensure long-term access to both legacy and next-generation chip technologies across all operational domains. Dependence on fragile semiconductor supply chains is a major vulnerability when essential systems must continue to operate despite supply interruptions. The availability of components or modules that can be used as generically as possible, such as programmable chips and chipsets, is a strategic priority anchored in the Armament Policy of the Federal Council. Consequently, collaborative infrastructures such as the Swiss Chip FabLab reinforce Switzerland's strategic foundation, strengthening its resilience, and ensuring long-term technological readiness.

Rheinmetall, Zürich

RHEINMETALL

Reto Maurer, Senior Vice President Sales, Rheinmetall AG

Reto Maurer, Dipl. Masch. Ing. FH, SVP Sales at Rheinmetall Air Defence and President of Swiss ASD, is an expert in ground based short range air defence systems. With extensive experience in both, the defence industry but also the governmental administration (armasuisse), he has been instrumental in advancing technologies and partnerships that strengthen national and international security capabilities. Additionally, he is President of SWISS ASD, SWISSMEM's industry sector of member companies active in Aeronautics, Security and Defence.

Abstract

The example of Rheinmetall's world-leading "Skynex" and "Skyranger" air defence systems demonstrates the extraordinary capabilities that are possible today with the help of modern semiconductor chips.

Swissmem, Zürich

SWISSMEM | Semiconductor

Dr. Adriaan Spierings,
Head of Swissmem industry sector Semiconductor

After his studies in Mechanical Engineering and Business Administration at ETH Zurich, he had several positions in industry and research. In 2005 he started building up a research group on metal additive manufacturing, which he has been leading for over 18 years. During that time, he initiated the Swiss Additive Manufacturing Group SAMG at Swissmem.

In 2023 Adriaan joined Swissmem, taking over the SAMG group and the semiconductor industry sector that was founded in the same year. Together with a strong industry board, he is building up and strengthening this industry sector to support and give the industry visibility in Switzerland and a voice.

Session 2:
Trends, challenges and opportunities for the Swiss industry in chip design

Session moderation		**Dr. Alain-Serge Porret, CSEM**
10:50 – 11:10	**Keynote:** World's fastest AI inference with Wafer Scale Engine. Against all odds	**Jean-Philippe Fricker, Cerebras**
11:10 – 11:20	From Miniaturization to Full Solutions: Navigating Innovation and Challenges in Chip Design for Sensors	Dr. Thomas Uehlinger, Sensirion AG
11:20 – 11:30	Niche Beats Scale: Ultra-Low-Power CMOS with a Swiss Fab and a Global Footprint	Peter Brandt, EM Microelectronic
11:30 – 11:40	Building a deep-tech semiconductor company in Switzerland	Prof. Amin Shokrollahi, Kandou
11:40 – 12:00	Discussion, moderated Q&A	Dr. Alain-Serge Porret, CSEM

Cerebras Systems, Inc. , Sunnyvale

Jean-Philippe Fricker,
Founder and Chief System Architect, Cerebras Systems
Before co-founding Cerebras, J.P. was Senior Hardware Architect at rack-scale flash array startup DSSD (acquired by EMC and Dell). Prior to DSSD, J.P. was Lead System Architect at SeaMicro where he designed three generations of fabric-based computer systems. Earlier in his career, J.P. was Director of Hardware Engineering at Alcatel-Lucent and Director of Hardware Engineering at Riverstone Networks. He holds an MS in Electrical Engineering from EPFL – École Polytechnique Fédérale de Lausanne, Switzerland, and has authored 42 patents.

Abstract
This keynote explores how Cerebras' revolutionary Wafer Scale Engine is redefining AI inference, achieving unprecedented speed and efficiency in chip design. Against the backdrop of global supply chain constraints and fierce competition, we'll discuss how bold innovation and Swiss engineering talent can address critical challenges and seize emerging opportunities. Attendees will gain insights into the technical breakthroughs behind wafer-scale computing, its impact on AI workloads, and the strategic advantages it offers the Swiss semiconductor industry. Join us to discover how "against all odds", cutting-edge technology is shaping the future of AI hardware and Switzerland's role within it.

Sensirion AG, Stäfa

SENSIRION

Dr. Thomas Uehlinger, Head R&D, ASIC

Thomas Uehlinger, born in 1983, studied Experimental Physics at ETH Zurich, earning his diploma in 2008 and a doctorate in ultracold quantum gases in 2014. He joined Sensirion AG in Stäfa the same year, contributing to sensor innovation as an R&D Engineer before leading the development of the world's smallest reflow-solderable optical CO_2 sensor. From 2021 to 2024, he headed the optics cluster, advancing miniaturized photoacoustic gas sensors for diverse applications. Since the beginning of 2025, he serves as Head of R&D ASIC, advancing the integrated circuit designs driving next-generation sensor technologies.

Abstract

Sensor technology is advancing rapidly, driven by the need for miniaturization, scalability, and integrated functionality. Combining sensing elements with on-chip signal processing and calibration unlocks significant gains in performance and cost efficiency. Yet, Swiss chip design companies face growing challenges: soaring development costs, pressure to adopt smaller nodes, and geopolitical uncertainties. This talk presents strategies for iterative innovation and deep value-chain integration—leveraging the strengths of Switzerland's high-tech ecosystem. Finally, we examine the shift toward holistic sensing solutions, where hardware, software, and connectivity converge to create new opportunities for delivering differentiated value to end customers.

EM Microelectronic, Marin-Epagnier

em microelectronic
A COMPANY OF THE SWATCH GROUP

Peter Brandt, VP Development, EM Microelectronic – Marin SA

Seasoned semiconductor leader and board member with 25+ years of experience across consumer electronics, mobile, test & measurement, wireless IoT, and automotive. Extensive experience in multinational corporations and startups, driving engineering and organizational transformations. Proven track record in pragmatic change management and aligning technology, teams, and product strategy to deliver measurable business results. As VP Development at EM Microelectronics, he collaborates with multidisciplinary teams to develop and bring state-of-the-art ultra-low-power technologies to a variety of markets.

Abstract

Switzerland no longer competes in semiconductor manufacturing through scale, but through focus. As the country's only CMOS wafer fab, EM Microelectronics uses its Swiss manufacturing base to develop differentiated ultra-low-power technologies tailored to specific application needs. At the same time, external foundries are leveraged where advanced nodes or very high volumes are required—without abandoning a consistent ultra-low-power design philosophy.

In a rapidly changing global market, this approach requires strong focus combined with continuous evolution of design methodologies, platform strategies, and go-to-market models. This talk discusses how combining an in-house wafer fab with a selective global foundry strategy and an agile development mindset, enables a long-term Swiss relevance in a highly competitive global semiconductor ecosystem.

Kandou AI, St-Sulpice

Prof. Amin Shokrollahi,
Found and Chief Technology Officer, Kandou AI

Prof. Amin Shokrollahi, is a mathematician, computer scientist, and technology entrepreneur. He was a researcher at Bell Labs, served as Chief Scientist of Digital Fountain, and is Professor of Mathematics and Computer Science at EPFL. He is the Founder and long-time CEO of Kandou, a deep-tech semiconductor company headquartered in Switzerland. He is the author of more than 230 peer-reviewed publications, an inventor or co-inventor on approximately 300 patents, an IEEE Fellow, recipient of the IEEE Hamming Medal, and the Mustafa Prize

Abstract

Switzerland has a long and diverse tradition in semiconductor innovation, spanning applications from sensors and power electronics to precision instrumentation. Yet building a deep-tech semiconductor company—rooted in fundamental research, long development cycles, and globally competitive IP—remains particularly challenging. Key hurdles include attracting and retaining highly specialized talent, securing patient and knowledgeable investors, gaining international mind-share, and scaling from research excellence to market impact. In this talk, I will briefly outline these challenges and share practical lessons from our experience in addressing them while building a deep-tech semiconductor company in Switzerland.

CSEM, Neuchâtel

Dr. Alain-Serge Porret,
Vice President of Integrated & Wireless Systems, CSEM

Dr. Alain-Serge Porret is Vice President of Integrated & Wireless Systems at CSEM, where he leads the development of energy optimized, application specific solutions for autonomous connected devices and smart vision systems. His team's expertise spans ultra low power wireless communication, sensing, remote powering, secure embedded software, and custom ASIC design.

He previously spent 13 years in Silicon Valley, co founding several consumer electronics start-ups. He holds a Ph.D. from EPFL, where his research helped advance the field of ultra low power CMOS radio chips.

Session 3:

Trends, challenges and opportunities for the Swiss industry in metrology along the semiconductor value chainadvanced packaging

Session moderation		**Dr. Yasin Ekinci, PSI**
13:15 – 13:35	**Keynote:** Inspection and Metrology challenges in Semiconductor Advanced Packaging	Thierry Eme, Cohu
13:35 – 13:45	Building a Swiss Innovation Ecosystem focused on Semiconductor Metrology & Inspection	Dr. Procopios Constantinou, Park Innovaare / PIA
13 :45 – 13 :55	Motion System Solutions for Metrology and Inspection Challenges in Semiconductor Manufacturing	Hervé Stämpfli, ETEL SA
13:55 – 14:05	Closing the Metrology Gaps in Contamination Control at Front-end Manufacturing of Leading-Edge Semiconductors	Dr. Ali Ozhan Altun, Unisers AG
14:05 – 14:15	How Robust Nanoscale Metrology is Mission-Critical for Semiconductor Manufacturing	Dr. Dominik Ziegler, Nanosurf AG
14:15 – 14:35	Discussion, moderated Q&A	Dr. Yasin Ekinci, PSI

Cohu, La Chaux-de-Fonds

Thierry Eme, Director of Innovation, Cohu

Semiconductor industry leader with over 25 years of experience in inspection, metrology, and manufacturing technologies. He holds a Master's degree in Microengineering from the Swiss Federal Institute of Technology in Lausanne (EPFL) and completed his diploma work at the University of California, Berkeley, focusing on robotics. Thierry joined Ismeca Semiconductor Europe in 1999 as a Machine Vision Engineer and was promoted Vice President of Technology in 2007. Throughout his career, he has held multiple senior management roles across inspection and metrology organizations in Switzerland and the United States. Serving today as Director of Innovation for Cohu's Inspection and Metrology Division.

Abstract

The rapid growth of artificial intelligence is driving strong demand for High Performance Computing (HPC) devices, leading to new semiconductor architectures and manufacturing processes. This evolution has fostered the Middle-End (ME) market, driven by advanced memory, CMOS, HPC, and GPU technologies. As Moore's Law scaling reaches its limits, the industry is shifting toward 2D, 2.5D, and 3D packaging, significantly increasing device complexity and I/O density. These challenges place inspection and metrology solutions at the core of manufacturing process control and yield optimization.

Switzerland Innovation Park Innovaare, Villigen

Dr. Procopios Constantinou, Project Manager, Switzerland Innovation Park Innovaare

Dr. Procopios Constantinou is spearheading the Semiconductor Metrology & Inspection Innovation Hub at Park Innovaare. He earned his PhD in Physics at the London Centre for Nanotechnology in University College London, studying two-dimensional dopant layers in silicon with synchrotron methods and resistless EUV patterning. He then joined the Paul Scherrer Institute, first as a postdoctoral researcher and later as Project Scientist, where he led PSI's collaboration with Microsoft Quantum on material characterization of superconductor–semiconductor hybrid heterostructures for quantum devices.

Abstract

The Semiconductor Metrology & Inspection (SeMI) Innovation Hub, spearheaded by Park Innovaare in collaboration with PSI, Swiss industry, and institutional partners, establishes a new proactive ecosystem in a domain where Switzerland already holds strong technological leadership. The initiative builds on PSI's world-class assets and scientific excellence - most notably, its world-record setting capabilities in X-ray imaging (4 nm resolution) and EUV lithography (6 nm half-pitch). By bridging the critical gap between frontier research, industrial innovation, and commercialization, the SeMI Hub aims to strengthen the Swiss semiconductor sector by establishing a collaborative platform where innovation can progress more rapidly and with greater impact and visibility. This presentation will outline the Hub's vision, current status, and opportunities for participation.

ETEL SA, Môtiers

Hervé Stämpfli, Head of product management, ETEL

Hervé Stämpfli obtained his Master of Science in Mechanical Engineering at the Swiss Federal Institute of Technology in Lausanne, Switzerland, in 1997. He started as an R&D engineer at ETEL, part of the HEIDENHAIN Corporate Group, in 1999, and has held various positions in R&D, sales and marketing over the past 25 years. Having led the Technical Sales department in Switzerland for a few years, he moved to the United States, where he was Technical Manager of ETEL' subsidiary in Schaumburg, Illinois. After returning to Switzerland, Hervé took over the Motion System Product Management position and is now the Head of Product Management at ETEL

Abstract

As semiconductor manufacturing advances toward ever smaller nodes and more complex 3D device stacks, metrology and inspection play an increasingly critical role in process control. This talk reviews the fundamentals of process control and the unique precision, stability, and environmental insensitivity required by measurement intensive systems. It then outlines key performance requirements—accuracy, repeatability, stability, and speed—and examines the contributors to system capability, including vibration isolation, thermal management, motion system metrology, and advanced control. The presentation also highlights how motion system architecture enables higher performance through thoughtful mechanical design and metrology integration, addressing challenges essential to both current production demands and long term industry evolution

Unisers AG, Zürich

Dr. Ali Altun, Co-founder and CTO, Unisers

Dr. Altun has more than 15-year experience in optical spectroscopy and nanotechnology. Prior to his position at UNISERS AG, he worked at ETH Zurich, Lawrence Livermore National Laboratories and Korean Institute of Machinery and Materials. He has a Ph.D. degree from ETH Zurich, a M.Sc. degree from KAIST (Korea Advanced Institute of Science and Technology), S. Korea and B.Sc. degree from METU, Turkey.

Abstract

Effective classification of particle adders down to sub-10nm has become increasingly more important in process and tool development, validation and monitoring in leading-edge semiconductor fabrication. Increased complexity of 3D stacked geometries of new generation logic and memory devices require even stringent contamination control to eliminate costly excursions. This presentation will introduce a novel particle classification technology for unpatterned monitor wafers with sub-10nm sensitivity.

Nanosurf AG, Liestal

Dominik Ziegler, CEO, Nanosurf

Nanosurf AG is a leading manufacturer of atomic force microscopes, where Dominik Ziegler drives strategic growth, product innovation, and operational excellence following the company's acquisition by Lab14. With a strong background in nanotechnology and instrumentation, he previously served as CTO of Nanosurf and founded Scuba Probe Technologies. Dominik has held research roles at Lawrence Berkeley National Laboratory, University of Tokyo and EPFL Lausanne. He holds a PhD from ETH Zurich and has extensive experience bridging cutting-edge research with industrial applications.

Abstract

As semiconductor devices continue to shrink in size and increase in complexity, nanoscale metrology becomes increasingly mission-critical. Nanosurf plays a pivotal role in the semiconductor ecosystem through the development of high-performance atomic force microscopes that enable sub-angstrom metrology of precision optics for lithography and solutions for automated quality control across many wafer-level processes, high-throughput roughness measurements and semiconductor failure analysis. By delivering state-of-the are accuracy, robustness, and seamless integration into production and R&D environments, Nanosurf empowers the semiconductor industry to improve yield, accelerate innovation, and ensure reliability across all advanced manufacturing processes.

PSI, Bern

Dr. Yasin Ekinci, Head of Laboratory for X-ray Nanoscience and Technologies, Paul Scherrer Institute

The lab hosts 6 research groups, about 80 people and operates 3 synchrotron and X-ray FEL beamlines. He obtained his Ph.D. at Max-Planck Institute in Göttingen, Germany. He worked on various topics of nanoscience and technology, including atom optics, surface science, EUV lithography, resist materials, coherent scattering, lensless imaging, plasmonics, metamaterials, semiconductor nanostructures, and biosensors. He is author of more than 300 publications, including papers, book chapters, and patent applications. He received Young Investigator Award of Swiss Society for Optics and Microscopy. He is a fellow of SPIE.

Session 4:

Trends, challenges and opportunities for the Swiss industry in advanced packaging

Session moderation		**Cemal Aydogan, Hitachi Energy AG**
15:05 – 15:25	**Keynote:** Novel solutions from ZEISS supporting Advanced Packaging technology needs	Martin Dietzel, Carl Zeiss SMT
15:25 – 15:35	Si & SiC power semiconductor packaging - Baseline for our power grid today and in the future	Tobias Keller, Hitachi Energy AG
15:35 – 15:45	Advanced Packaging as a Multi-Domain Engineering and Control Problem	Rok Vintar, Cosylab AG
15:45 – 15:55	Advanced Packaging & Heterogeneous Integration: Opportunities for Switzerland's Semiconductor Industry	Silvio Muschter, Swissbit AG
15:55 – 16:15	Discussion, moderated Q&A	Cemal Aydogan, Hitachi Energy AG

Carl Zeiss SMT GmbH, Zürich

M. Dietzel, Director Product Strategy, Carl Zeiss SMT GmbH, Zürich
After graduating in Physics from the Technical University of Munich, Martin started his career in a company building professional robotic telescopes and observatories worldwide. In 2011 he joined ZEISS and held several management positions in product management and as a business line manager. In his current role Martin is Head of Product Strategy Beyond and manages ZEISS Semiconductor Manufacturing Technology's (SMT) business development activities targeting market fields beyond SMT's current business portfolio like Advanced Packaging and Photonics.

Abstract
In-line metrology and process control are technologies with growing importance, particularly relevant for advanced packages that utilize complex 3D stacking technologies. This presentation highlights several key technological challenges associated with the use of in-line package metrology and shows novel solutions from ZEISS to extract data from these complex 3D structures and presents solutions that can be employed to overcome these obstacles.

Hitachi Energy Ltd, Lenzburg

HITACHI

Tobias Keller, Vice President - Head of Global Product Management, Portfolio & Marketing, Hitachi Energy

Tobias Keller graduated from University of applied science Aargau with a degree in power electronics, thermodynamics and el. machines. He joined ABB's Excitation and Synchronizing business. He was the Vice President global Products and Marketing. Afterwards he held the Vice President position for Vehicle Integration Engineering in ABB's traction business. Since 2019, he is the Vice President global Product Management, Portfolio & Marketing in Hitachi Energy Semiconductor. Tobias Keller is a senior member of IEEE.

Abstract

Compared to today, there were almost no power semiconductors in the primary power grid 25 years ago. However, much has gone since then, the power semiconductors have become more reliable and efficient and are now indispensable in the power grid. Whether it is power semiconductors that are used for the integration of renewable energy sources (e.g. solar and wind) or for the transport of energy, such as in HVDC (High Voltage Direct Current) or FACTS (Flexible Alternating Current Transmission Systems), power semiconductors today make a significant contribution to the stability and performance of the power grid. With the availability of SiC power semiconductors that enable even higher performance, this journey with the best of the two worlds Si and SiC will remain very exciting for packaging in the future.

Cosylab Switzerland AG, Brugg

COSYLAB
Advancing humanity. Engineering remarkable.

Rok Vintar, Engineering Group Lead, Cosylab

Rok Vintar is a generalist with more than a decade of technical and managerial experience in a wide spectrum of industrial and research projects. He has been working with customers from tough-tech fields such as semiconductor equipment manufacturing, industrial fusion, particle accelerators for research, as well as for cancer treatment.
Rok brings a systems engineering mindset combined with a deep understanding of different project aspects (technical, managerial, business, and people) and acts as a strong connection point between those disciplines.

Abstract

As traditional transistor scaling slows, advanced packaging has become a critical enabler of semiconductor progress. Chiplets, heterogeneous integration, and 2.5D/3D architectures are now shaping system performance, power efficiency, and scalability in AI, HPC, and advanced electronics, while simultaneously introducing challenges that go beyond materials and individual process steps. Advanced packaging is increasingly a multi-domain engineering problem, dominated by warpage, alignment, thermal stress, and complex tool interactions. This talk focuses on the role of control, metrology, and system-level orchestration in managing this complexity, as these capabilities emerge as decisive success factors. Rok will highlight key lessons learned by Cosylab across industries where system complexity is a defining characteristic.

**Swissbit AG,
Bronschhofen**

Silvio Muschter, Chief Technology Officer, Swissbit AG and member of the founding team (2001)
For over two decades he has steered Swissbit's technology vision and corporate strategy in roles including CTO, COO, and eight years as CEO. As an industry expert in electronics, embedded systems, and semiconductor back end integration, he drives innovation across high reliability memory, security, and advanced packaging, and builds partnerships that strengthen European supply chain resilience. Earlier in his career he held roles at Infineon Technologies and Siemens Switzerland. He holds a degree in electrical engineering.

Abstract
Advanced packaging is becoming increasingly important for Swiss and European semiconductor players seeking higher performance, reliability, and supply chain resilience. This talk introduces heterogeneous integration, from today's System in Package (SiP) solutions toward emerging System on Package concepts, and shares practical insights from operating Europe's only memory IDM with in house design, assembly, and test capabilities. Drawing on real industrial experience, we highlight key considerations such as substrates for chiplet based architectures and show how local companies can benefit from collaboration within Europe's growing advanced packaging ecosystem.

**Hitachi Energy AG,
Lenzburg**

Cemal Aydogan, Senior Engineer, Hitachi Energy
He has a MSc in Nanosciences and Physics and many published SPIE Papers. He was leading FEOL processes at IMPS Fraunhofer, Bosch, Infineon and Tübitak. He was on the advisory board for the establishment of the CMOS/MEMS fab at Fraunhofer and Tübitak. He is currently working for external founding projects and is the president of the Swissmem SEMI industry sector.

Panel discussion with keynote speakers:

"The real opportunities for the Swiss semiconductor industry facing the current global trends and conditions"

Seraina Frost,
SECO

Jean-Philippe Fricker,
Cerebras

Thierry Eme,
Cohu

Martin Dietzel
Zeiss SMT

Alain-Serge Porret,
CSEM

VDL ETG, Trübbach

VDL ETG SWITZERLAND

Hans Priem, VP Business Development, VDL ETG
After having finalized his Masters in Business Economics at Tilburg University, Hans started his 10 year career with ASML. Based on his experience within Finance and Product Management, he joined Philips Electronics EMT to assume responsibility over the company's Installed Base Business.
Since 2011, Hans is with VDL ETG. He is responsible for VDLs Science & Industry-related activities: technology development, identifying new applications & markets, innovation management, growth acceleration. All based on VDLs ultra-precision machining & metrology, vacuum, opto-mechatronics, and handling competences.
Currently applied in semiconductor manufacturing, analytical, health care and space equipment.

16:15 – 16:45 – **Panel discussion with keynote speakers**

Registration

Swissmem SEMI member:	CHF 60
Non-member:	CHF 100

Please note:
For cancellations until February 27, 2026 a cancellation fee of CHF 50 is due.
For cancellations after February 27, 2026 CHF 100 are due.
Limited capacity of 150 people.

Please register directly on the website:
www.swissmem.ch/de/aktuelles/veranstaltungskalender/semiconductor-day-2026

Location

EPFL auditorium
Rue de la Maladière 71
CH-2000 Neuchâtel

- on foot
- public transport
- 1 Parking Centre de la Maladière
- 2 Parking Piscine Nid -du-Crô

Arrival by public transportation:
The EPFL Microcity is located very close to the train station and hence it is ideal to arrive by train.
From the train station to the event location it is around 10-15 minutes walking distance.

Arrival by car:
The closest public parking garage is «La Maladière» or «la piscine».

Contact

Dr. Adriaan Spierings
Head of industry sector Semiconductor
+41 44 384 48 31
a.spierings@swissmem.ch

Isabelle Haipt
Events and Assistance industry sectors
+41 44 384 48 72
i.haipt@swissmem.ch

Sponsors

Gold

csem

invest Neuchâtel

em microelectronic

A COMPANY OF THE SWATCH GROUP

Silver

cadence

COSYLAB
Advancing humanity. Engineering remarkable

CYBER TECHNOLOGIES

EUMETRYS
YOUR FAB'S PARTNER

HITACHI

Hilpert electronics

HYBRID SA

nanosurf

VDL ETG SWITZERLAND

ZEISS

Bronze

aptasic
bluetest
much more than asic test

Canton of Zurich
Department for Economic Affairs
Office for Economy

Innovation Zurich

HMT
microelectronic AG

Melexis
INSPIRED ENGINEERING

onsemi

SEMTECH

swissbit

SWITZERLAND INNOVATION
PARK INNOVAARE

SWISSMEM